Atty Docket No: 0553-0525

In re application of: Tsunenori SUZUKI et al. Serial No: Filed: Herewith For: Semiconductor Device And Manufacturing Method Thereof Art Unit: Examiner: Date of Deposit August 25, 2006 I hereby certify that this correspondence is bein deposited with the United States Postal Service Mail Post Office to Addressee' service is a addressed to: Commissioner for Patrick PATENT ASSIGNMENT COVER SHEET Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 Countries	103300743	ND TRADEMARK OFFICE "Express Mail" Mailing Label No. EV 82982
1. Name of Conveying Party(ies): Tsunenori SUZUKI, Ryoji NOMURA, Mikio YUKAWA, Nobuharu OHSAWA, Tamae TAKANO, Yoshinobu ASAMI and Takehisa SATO 2a. Name and Address of Receiving Party(ies): Name: Semiconductor Energy Laboratory Co., Ltd. Address: 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan 2b. Name and Address of Receiving Party(ies): Name: Address 3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other X Execution Date: 8/7/06; 8/14/06 4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: 8/7/06; 8/14/06 4. Patent Application No.(s) 4. Patent Application No.(s) Assigning Tsunend Address of Party to Whom Correspondence Concerning Document Should be Mailed: Address of Party to Whom Correspondence Concerning Document Should be Mailed: Address of Party to Whom Correspondence Concerning Document Should be Mailed: Address (Concerning Document Should be Mailed: Cook, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved: 1. Total Fee (37 CFR 3.41): \$40.00 7a. X Enclosed 7b. X Authorized to be Charged to Deposit Account For Any Deficiency (A duplicate copy of this page is attached) 9. Statement and Signature: 7 to the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Mark J. Murphy Name of Person Signing Signature Account For Any Deficiency Statement and Signature To the best of my knowl	In re application of: Tsunenori SUZUKI et al. Serial No: Filed: Herewith For: Semiconductor Device And Manufacturing Method Thered Art Unit: Examiner: PATENT ASSIGNM Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 Sir:	Date of Deposit August 25, 2006 Date of Deposit August 25, 2006 Date of Deposit
	1. Name of Conveying Party(ies): Tsunenori SUZUKI, Ryoji NOMURA, Mikio YUKAWA, Nobuharu OHSAWA, Tamae TAKANO, Yoshinobu ASAMI and Takehisa SATO 2a. Name and Address of Receiving Party(ies): Name: Semiconductor Energy Laboratory Co., Ltd. Address: 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan 2b. Name and Address of Receiving Party(ies): Name: Address 3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other X Execution Date: 8/7/06; 8/16/06; 8/7/06; 8/7/06; 8/7/06; 8/7/06; 8/14/06 4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: 8/7/06; 8/14/06; 8/7/06; 8	5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed: Edward D. Manzo, Esq. COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved: 1 7. Total Fee (37 CFR 3.41): \$40.00 7a. X Enclosed 7b. X Authorized to be Charged to Deposit Account For Any Deficiency 8. Deposit Account Number: 50/1039 (A duplicate copy of this page is attached) 9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Mark J. Murphy Name of Person Signing Signature Reg. No. 34,225
	4b. Patent No.(s)	

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Attorney Docket	
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ASSIGNMENT

Identity Of The Patent Application. I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled		
SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF which I executed herewith. If the patent application has already been filed, it received serial number		
and bears a filing date of		
The Assignee and The Assignment. I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd. a corporation organized according to the laws of Japan, having a place of business at 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.		
Payment Received. I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.		
Authorizations. I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.		
Further Acts. I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.		
In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.		
SUMENOVI SUZUKI	08/07/2006 Date	
	_ 	
Name: Ryoji NOMURA	08/16/2006	
Name: Ryoji NOMURA	Date	
Mikio , Ankawa Name: Mikio YUKAWA	08/07/2006 Date	
Nobahara Ohsawa Name: Nobuhara OHSAWA	0 8/0 1/2006 Date	

PATENT REEL: 018244 FRAME: 0415 Tamae Takano

Name: Tamae TAKANO

Date

Moshimobu Rami

Ot/07/2006

Name: Yoshinobu ASAMI

Takehisa Sato

Date

08/14/2006

Name: Takehisa SATO

Date

PATENT REEL: 018244 FRAME: 0416

RECORDED: 08/25/2006